AMENDMENTS TO THE CLAIMS

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

Listing of Claims:

1. (Currently Amended) A wiring-terminal-connecting adhesive, adapted to be used to electrically connect wiring terminals by interposing said adhesive between wiring substrates which are disposed so that said wiring terminals on faces of respective wiring substrates face each other, and heating said wiring substrates under application of a pressure, comprising

~~a curing agent capable of generating a free radical upon heating;~~

a radically polymerizable substance; ~~and~~

silicone particles having a modulus of elasticity of from 0.1 MPa to 100 MPa at 25°C and an average particle diameter of from 0.1 μm to 20 μm; and

electrically conductive particles.

2. (Original) The adhesive according to claim 1, wherein said silicone particles are contained in an amount of from 5 parts by weight to 200 parts by weight based on the weight of said radically polymerizable substance.

3. (Original) The adhesive according to claim 1, which further comprises a film-forming material.

4. (Original) The adhesive according to claim 3, wherein said film-forming material is a phenoxy resin.

5. (Previously Presented) The wiring-connecting-connecting adhesive according to claim 3, wherein said silicone particles are contained in an amount of from 5 parts by weight to 200 parts by weight based on 100 parts by weight of the total of said radically polymerizable substance and said film-forming material.

6.-7. (Cancelled)

8. (Withdrawn) A wiring-terminal-connecting adhesive film comprising:

a first layer formed of a composition containing a curing agent cable of generating a free radical upon heating, a radically polymerizable substance and silicone particles having a modulus of elasticity of from 0.1 MPa to 100 MPa at 25°C and an average particle diameter of from 0.1 μm to 20 μm; and

a second layer formed of a composition containing conductive particles, a radically polymerizable substance and silicone particles having a modulus of elasticity of from 0.1 MPa to 100 MPa at 25°C and an average particle diameter of from 0.1 μm to 20 μm, wherein

the first and second layers being formed in layers.

9. (Withdrawn) A method of connecting wiring terminals, comprising interconnecting wiring terminals electrically with the wiring-terminal-connecting

adhesive according to claim 1, wherein at least two wiring members have the connecting terminal individually.

10. (Withdrawn) The method of connecting wiring terminals according to claim 9, wherein at least one of said connecting terminals has

a surface which is formed of at least one selected from gold, silver, tin, a platinum group metal and indium-tin oxide.

11. (Withdrawn) The method of connecting wiring terminals according to claim 9, wherein at least one of said wiring members has

a substrate comprising at least one of an insulating organic material and glass.

12. (Withdrawn) The method of connecting wiring terminals according to claim 9, wherein at least one of said wiring members has

at least one selected from silicon nitride, silicone resin and polyimide resin, at its surface.

13. (Withdrawn) A wiring structure comprising at least two wiring members which have a wiring terminal individually, wherein

the wiring terminals of said wiring members are electrically interconnected with the wiring-terminal-connecting adhesive according to claim 1.

14. (Withdrawn) A method of connecting wiring terminals, comprising interconnecting wiring terminals electrically with the wiring-terminal-connecting adhesive according to claim 8, wherein at least two wiring members have the connecting terminal individually.

15. (Withdrawn) The method of connecting wiring terminals according to claim 14, wherein at least one of said connecting terminals has a surface which is formed of at least one selected from gold, silver, tin, a platinum group metal and indium-tin oxide.

16. (Withdrawn) The method of connecting wiring terminals according to claim 14, wherein at least one of said wiring members has

a substrate comprising at least one of an insulating organic material and glass.

17. (Withdrawn) The method of connecting wiring terminals according to claim 14, wherein at least one of said wiring members has

at least one selected from silicon nitride, silicone resin and polyimide resin, at its surface.

18. (Previously Presented) The wiring-terminal-connecting adhesive according to claim 4, wherein said silicone particles are contained in an amount of from 5 parts by weight to 200 parts by weight based on 100 parts by weight of the total of said radically polymerizable substance and said film-forming material.

19.-21. (Cancelled)

22. (Withdrawn) A wiring structure comprising at least two wiring members which have a connecting terminal individually, wherein

the connecting terminals of said wiring members are electrically interconnected with the wiring-terminal-connecting adhesive according to claim 2.

23. (Withdrawn) A wiring structure comprising at least two wiring members which have a connecting terminal individually, wherein

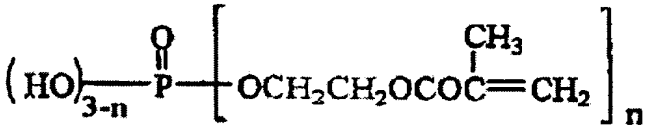
the connecting terminals of said wiring members are electrically interconnected with the wiring-terminal-connecting adhesive according to claim 3.

24. (Withdrawn) A wiring structure comprising at least two wiring members which have a connecting terminal individually, wherein
the connecting terminals of said wiring members are electrically interconnected with the wiring-terminal-connecting adhesive according to claim 4.

25. (New) The adhesive according to claim 1, wherein said electrically conductive particles have at least one of gold, silver, Ni, Cu, solder, carbon and a platinum group metal at least at the surface thereof.

26. (New) The adhesive according to claim 1, wherein the radically polymerizable substance includes, as a part thereof, a radically polymerizable

substance having a phosphoric ester structure represented by the following chemical formula (1)



(1)

wherein n is 1, 2 or 3.

27. (New) The adhesive according to claim 1, wherein said electrically conductive particles have at least one of gold, silver and a platinum group metal at least at the surface thereof.

28. (New) The adhesive according to claim 1, wherein said electrically conductive particles are included in the adhesive in an amount of 0.1 to 30 parts by volume of resin component of the adhesive.

29. (New) The adhesive according to claim 1, having a flowability of 1.3 to 3.0 as a value of flowability (B)/(A) represented by initial area (A) and the area (B) after heating and pressing, at 150°C and 2 MPa for 10 second, an adhesive 35 μm in thickness and 5mm x 5mm in size interposed between two sheets of glass of 0.7 mm in thickness and 15 mm x 15 mm in size.

30. (New) The adhesive according to claim 1, having a modulus of elasticity of from 100 to 3,000 MPa at 25°C after curing.